AMENDMENTS TO THE CLAIMS

- 1. (Currently amended) A copper-based alloy <u>eontaining comprising 5.0 to 10.0</u> <u>wt% of Zn. at least 2.8 to 5.0 wt% of Sn, 0.4 to 3.0 wt% of Bi, and satisfying 0 < Se ≤ 0.35 wt% to enable securing prescribed machinability and wholesome ness of a casting and exalt mechanical properties thereof., and a balance of Cu and unavoidable impurities.</u>
- 2. (Currently amended) A-The copper-based alloy according to claim 1, wherein it contains the Se of comprising 0.2 wt% or less of Se.
- 3. (Currently amended) A-<u>The</u> copper-based alloy according to claim 1, wherein it contains the Sn in a range of comprising 3.5 to 4.5 wt% of Sn.
- 4. (Currently amended) A-The copper-based alloy according to claim 1, wherein it further satisfies comprising 0 < P < 0.5 wt%.
- 5. (Currently amended) A-The copper-based alloy according to claim 1, wherein it further contains comprising Ni of 3.0 wt% or less of Ni.
- 6. (Currently amended) A copper-based alloy containing comprising at least Sn, Bi and Se and containing at least one non-solid solution substance formed of an alternative component for Pb in an amount of 1.0 vol% or more to enable suppression of occurrence of a casting defect. 5.0 to 10.0 wt% of Zn, 2.8 to 5.0 wt% of Sn, 0.4 to 3.0 wt% of Bi, $0 \le \text{Se} \le 0.35$ wt%, and a balance of Cu and unavoidable impurities, and further comprising 1.20 to 4.90 vol% of at least one selected from the group consisting of a non-solid solution substance secured with Bi and a non-solid solution substance secured with Bi and Se.
- 7. (Currently amended) A-The copper-based alloy according to claim 6, wherein it contains comprising the at least one non-solid solution substance secured with Bi.

- 8. (Currently amended) A-<u>The</u> copper-based alloy according to claim 6, wherein it eontains comprising the at least one non-solid solution substance secured with Bi and Se.
- 9. (Cancelled)
- 10. (Previously presented) A cast ingot produced using the alloy according to claim 1 and a liquid-contacting part formed of the cast ingot.
- 11. (Currently amended) A-<u>The</u> copper-based alloy according to claim 2, wherein it contains the Sn in a range of comprising 3.5 to 4.5 wt% of Sn.
- 12. (Currently amended) A-The copper-based alloy according to claim 2, wherein it further satisfies comprising 0 < P < 0.5 wt%.
- 13. (Currently amended) A-The copper-based alloy according to claim 3, wherein it further satisfies comprising 0 < P < 0.5 wt%.
- 14. (Currently amended) A-The copper-based alloy according to claim 2, wherein it further contains comprising Ni of 3.0 wt% or less of Ni.
- 15. (Currently amended) A-The copper-based alloy according to claim 3, wherein it further contains comprising Ni of 3.0 wt% or less of Ni.
- 16. (Currently amended) A-The copper-based alloy according to claim 4, wherein it further contains comprising Ni of 3.0 wt% or less of Ni.
- 17-18. (Cancelled)
- 19. (Previously presented) A cast ingot produced using the alloy according to claim 2 and a liquid-contacting part formed of the cast ingot.

- 20. (Previously presented) A cast ingot produced using the alloy according to claim 3 and a liquid-contacting part formed of the cast ingot.
- 21. (Previously presented) A cast ingot produced using the alloy according to claim 4 and a liquid-contacting part formed of the cast ingot.
- 22. (Previously presented) A cast ingot produced using the alloy according to claim 5 and a liquid-contacting part formed of the cast ingot.
- 23. (Previously presented) A cast ingot produced using the alloy according to claim 6 and a liquid-contacting part formed of the cast ingot.
- 24. (Previously presented) A cast ingot produced using the alloy according to claim 7 and a liquid-contacting part formed of the cast ingot.
- 25. (Previously presented) A cast ingot produced using the alloy according to claim 8 and a liquid-contacting part formed of the cast ingot.
- 26. (Cancelled)